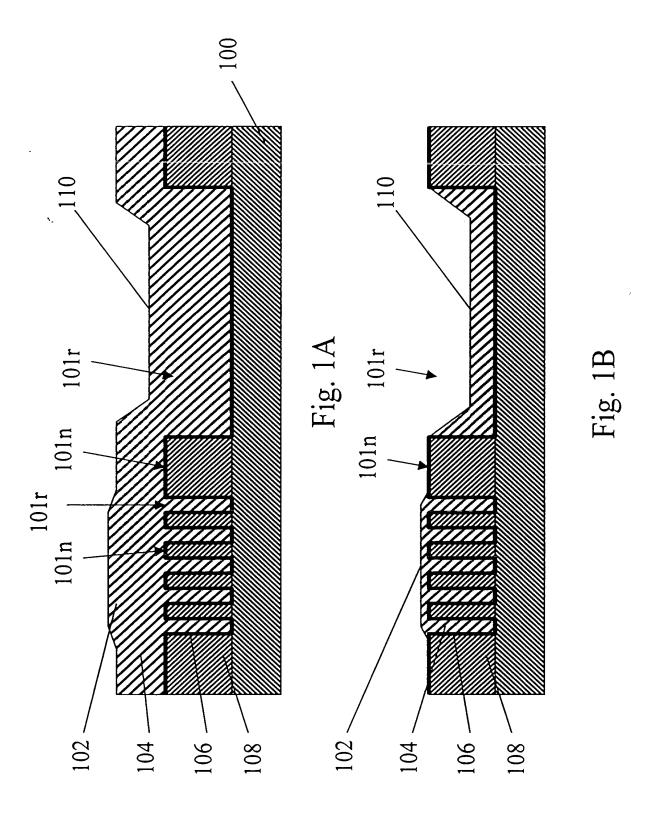
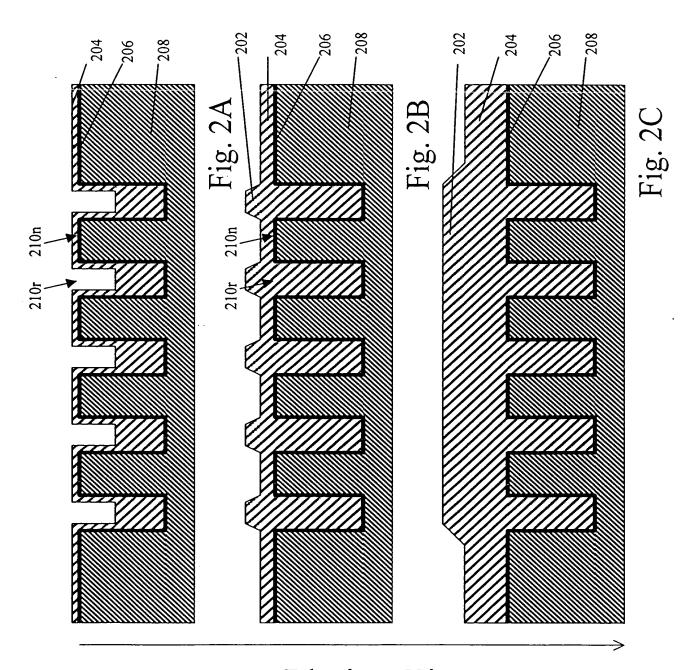
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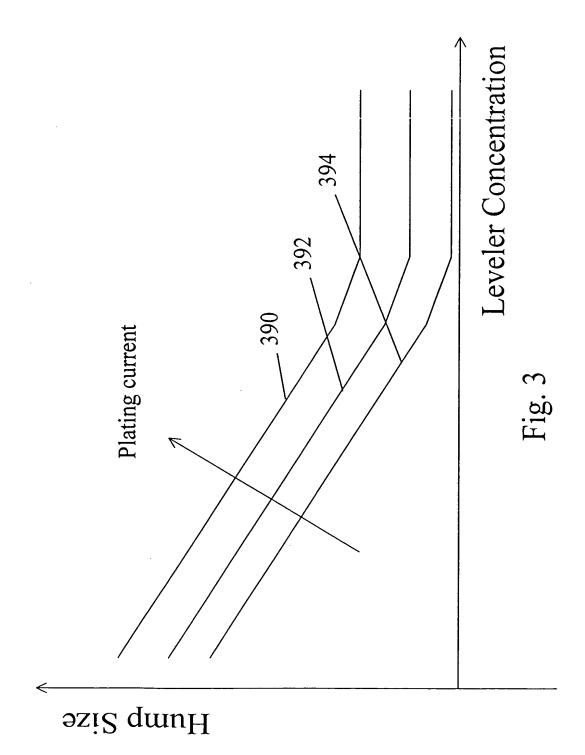
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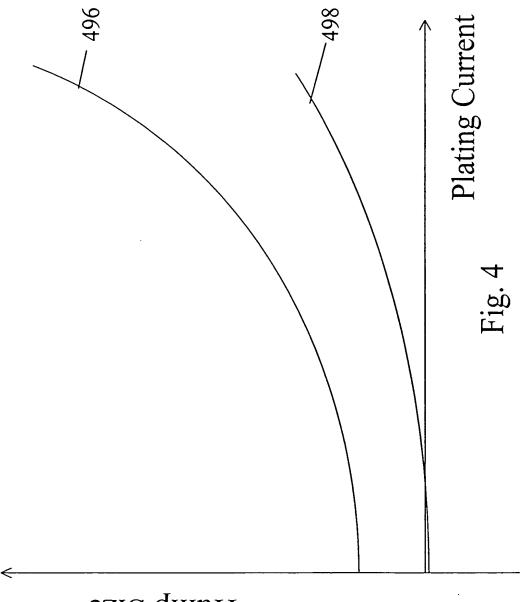


Plating Time

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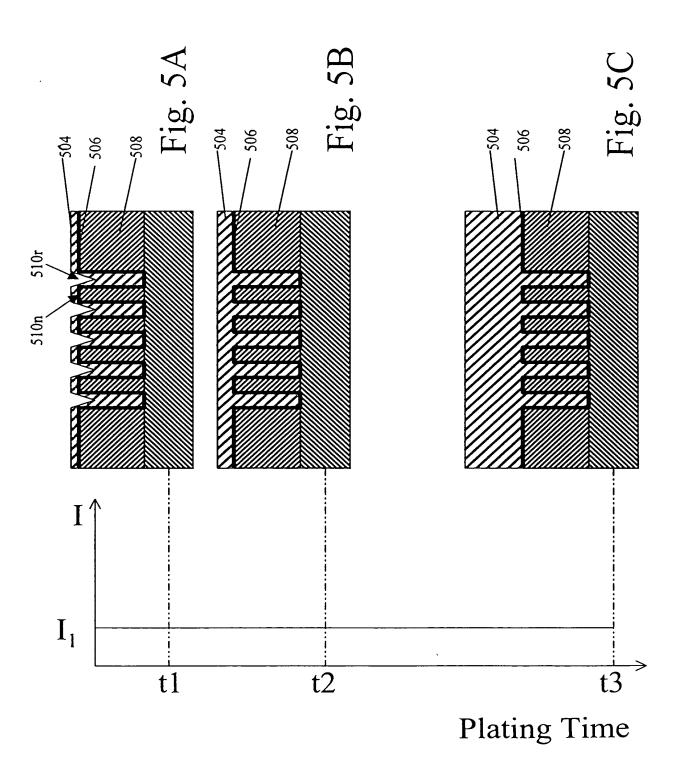


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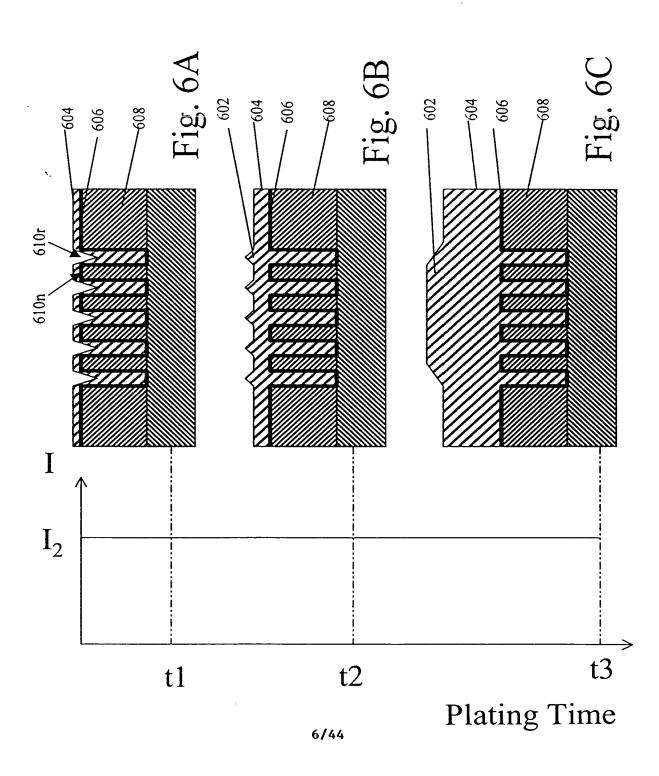
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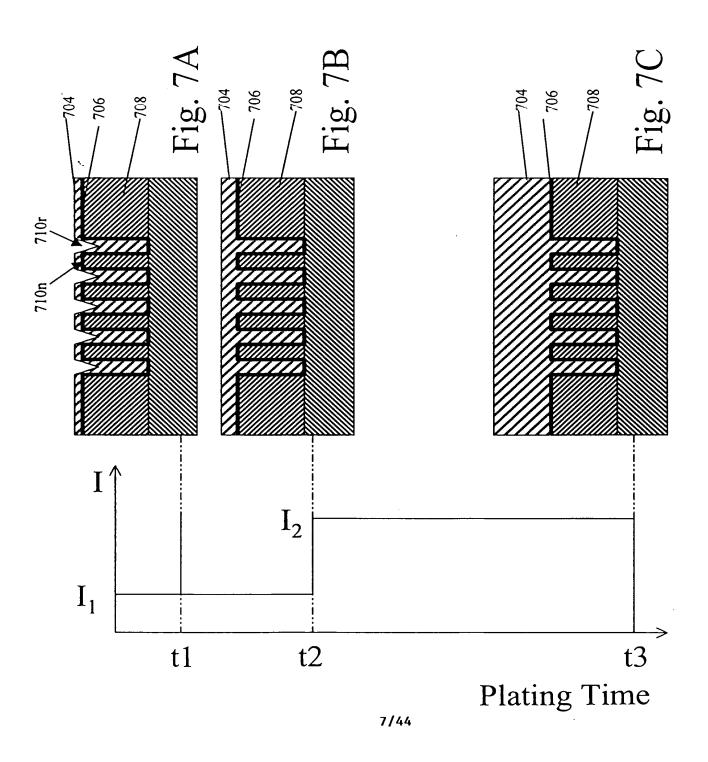


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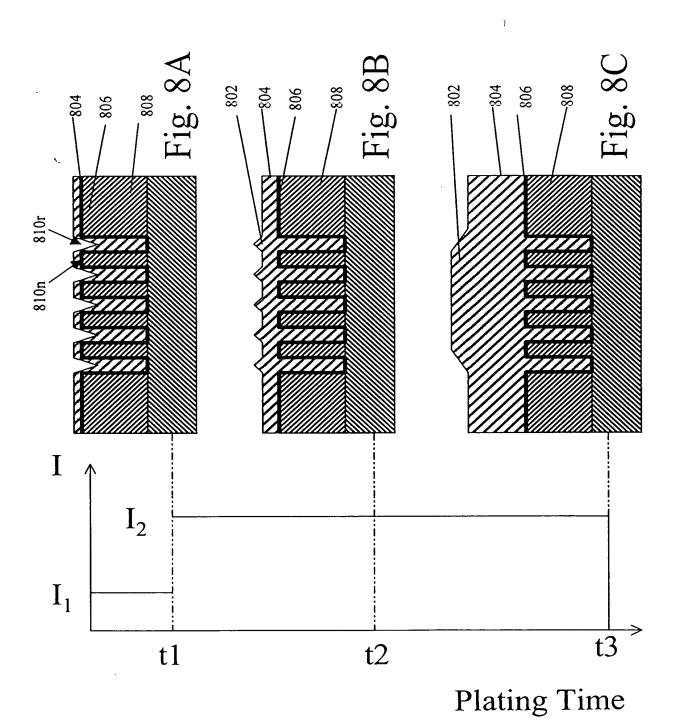
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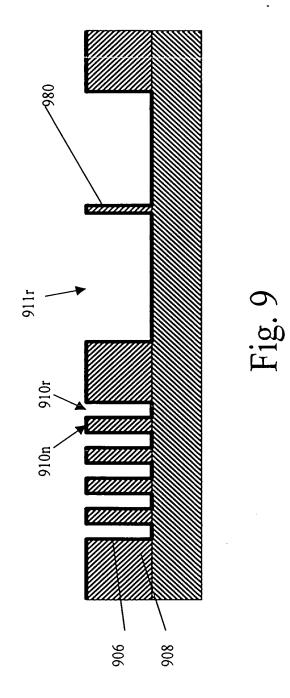


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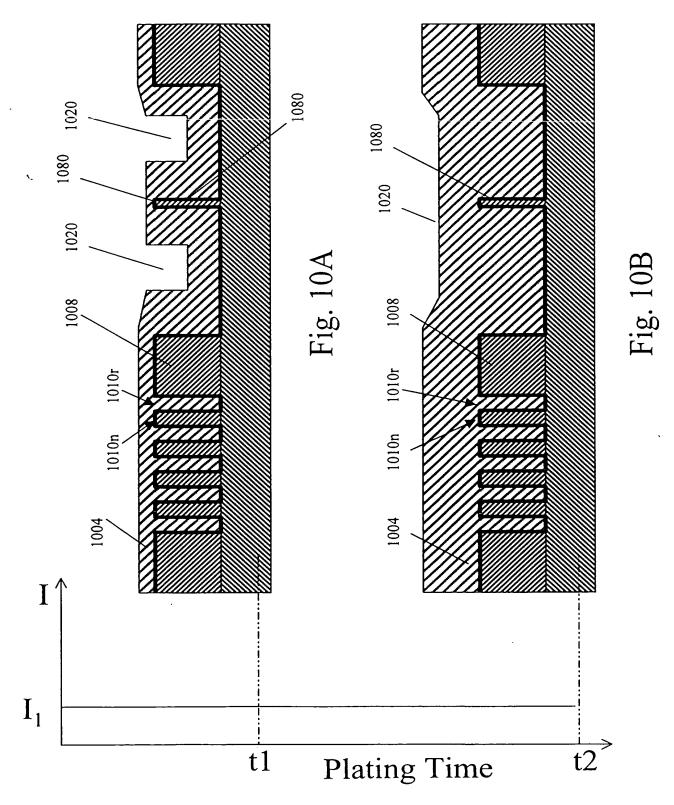


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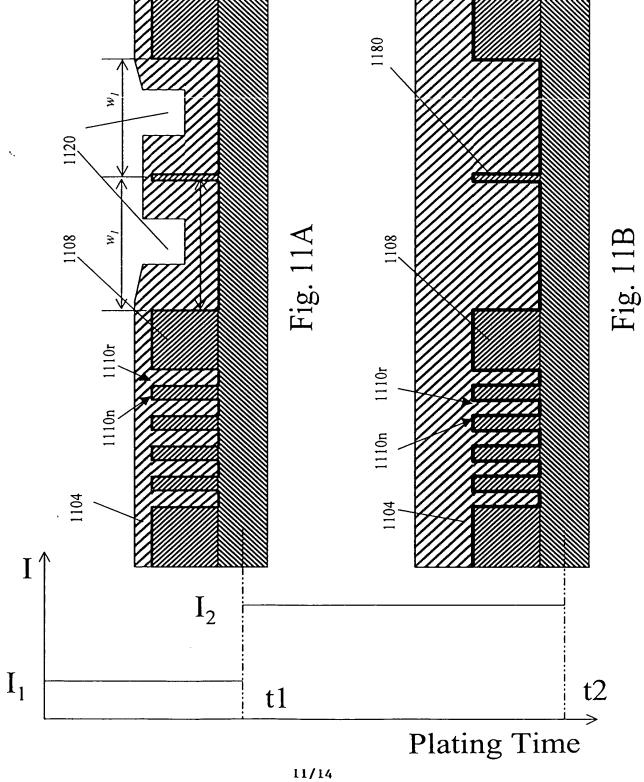
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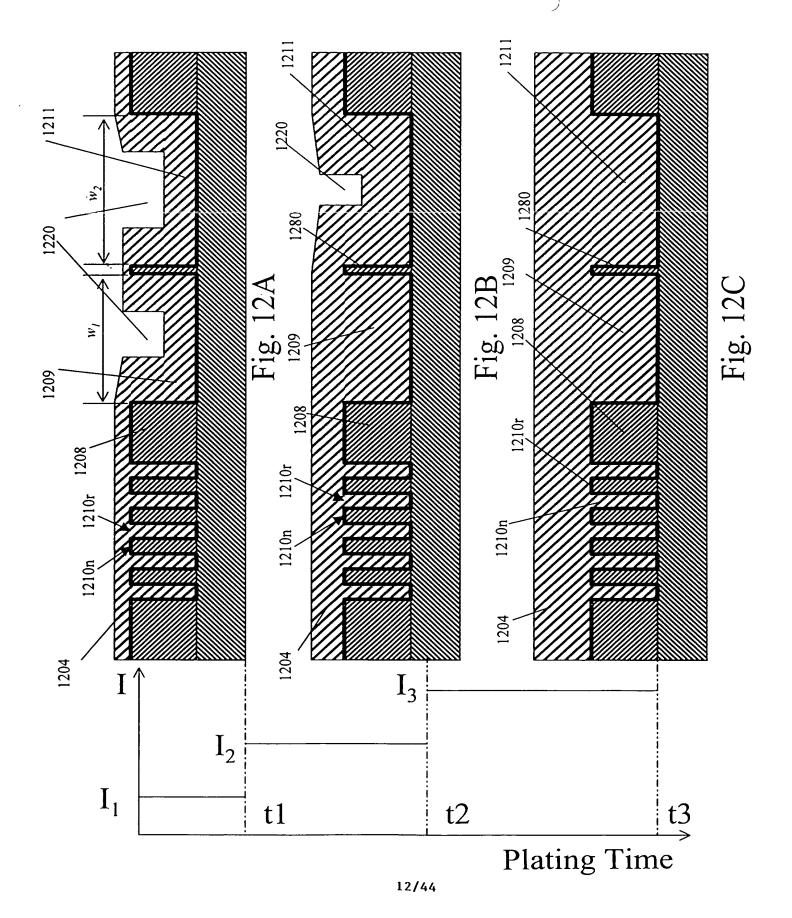
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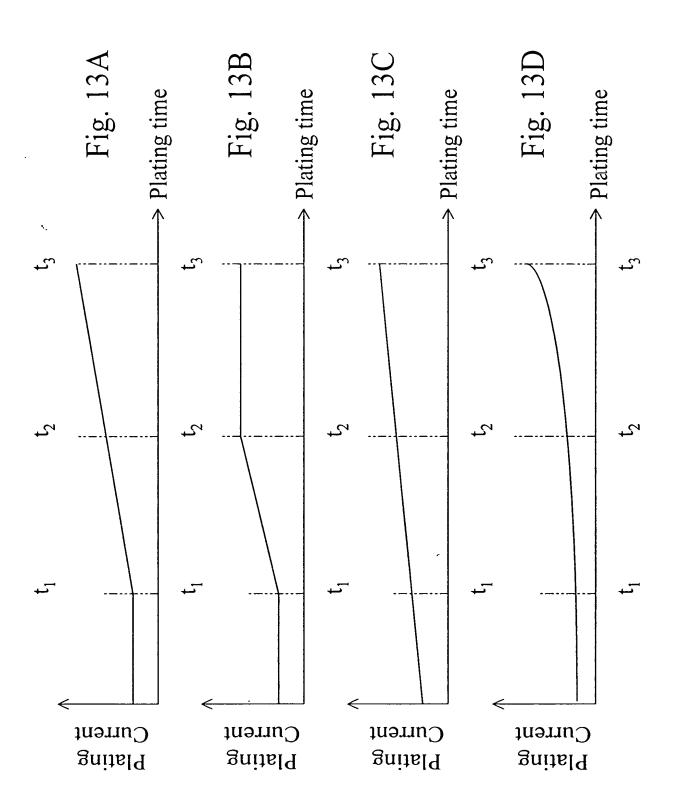
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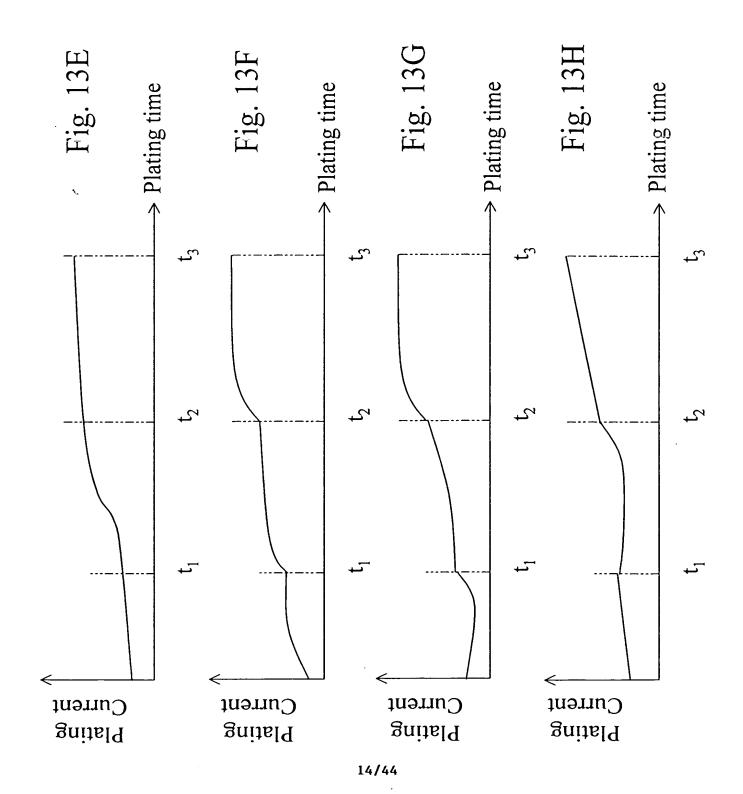
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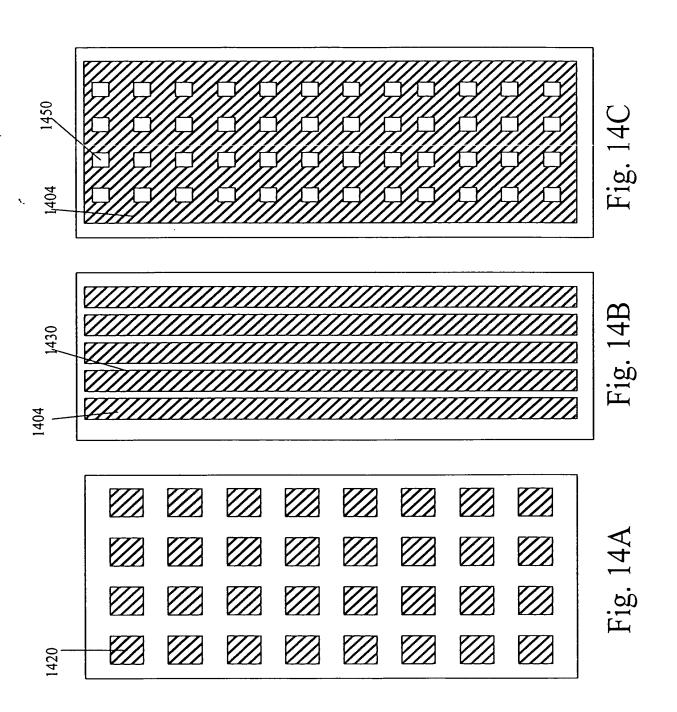
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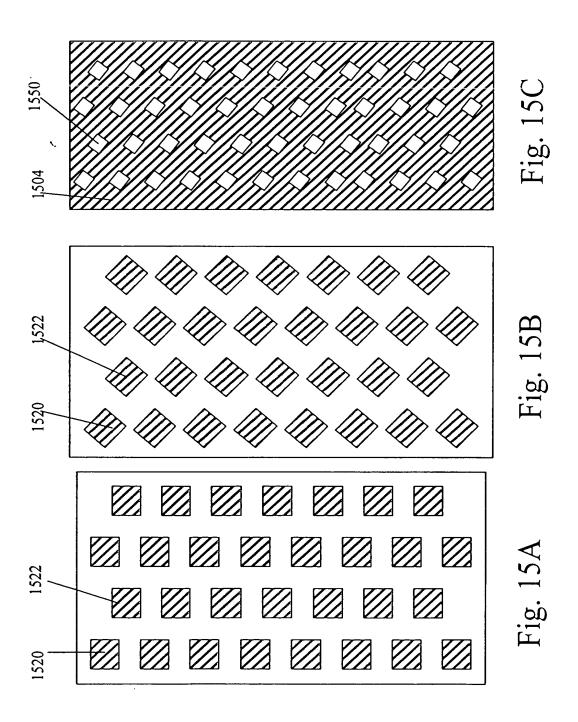
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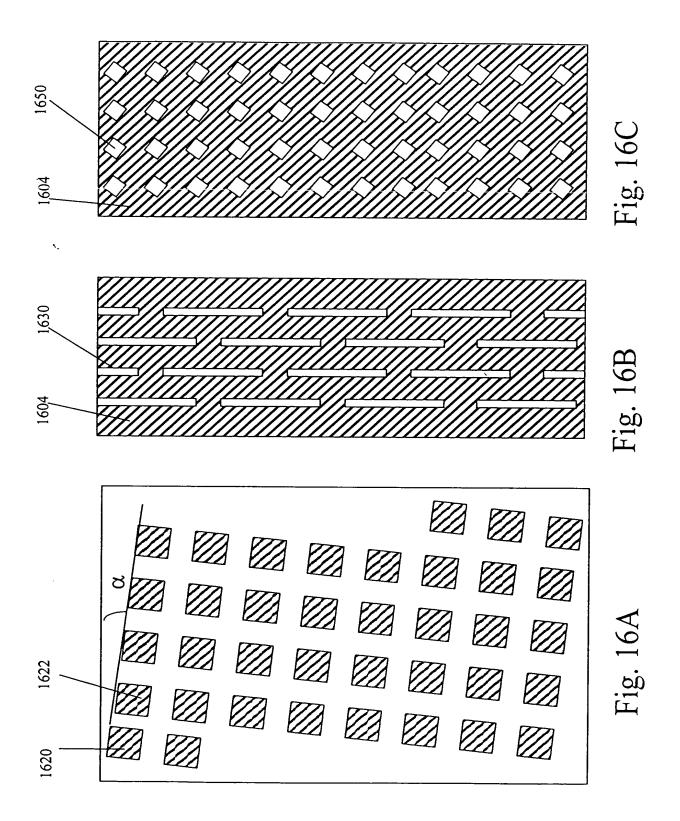
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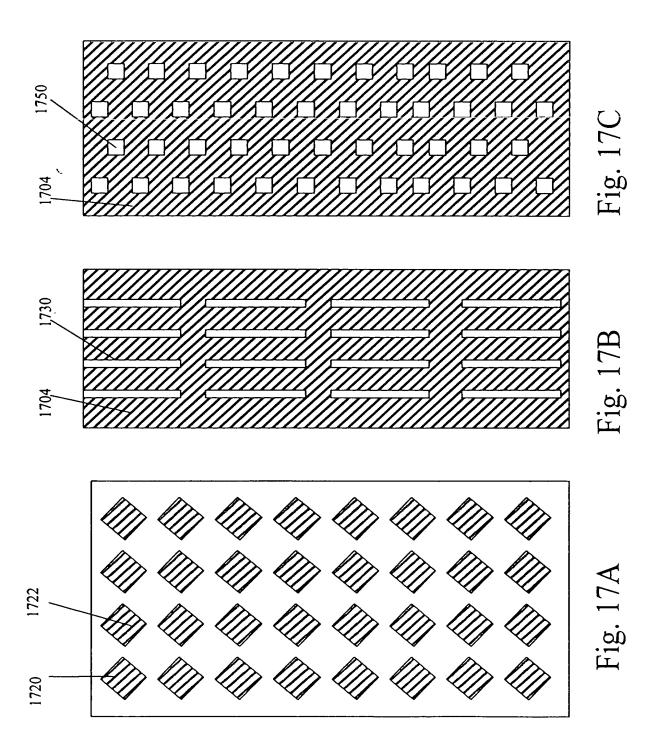
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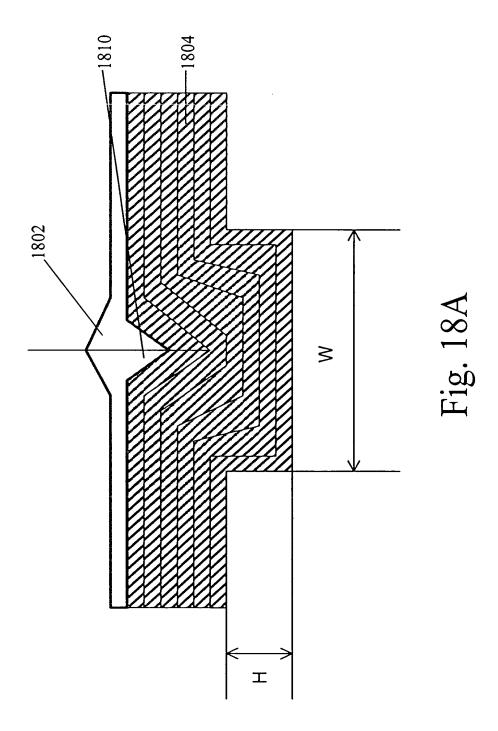
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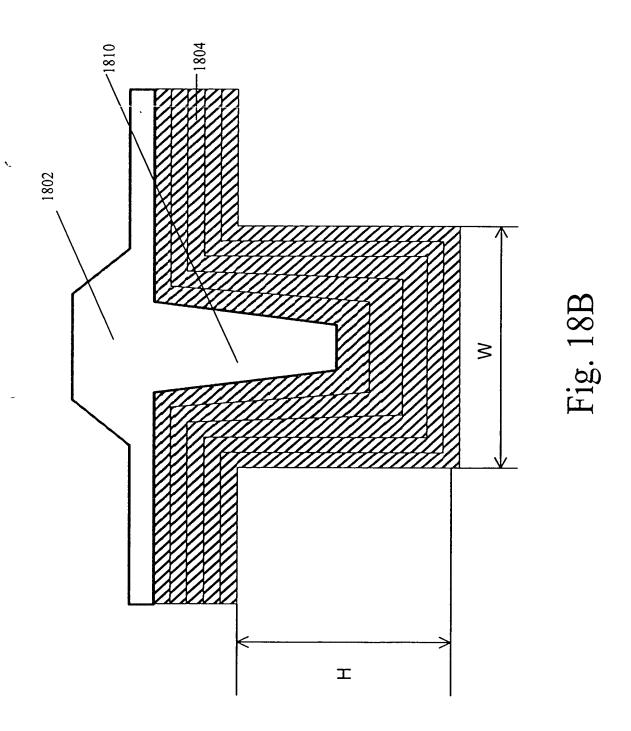


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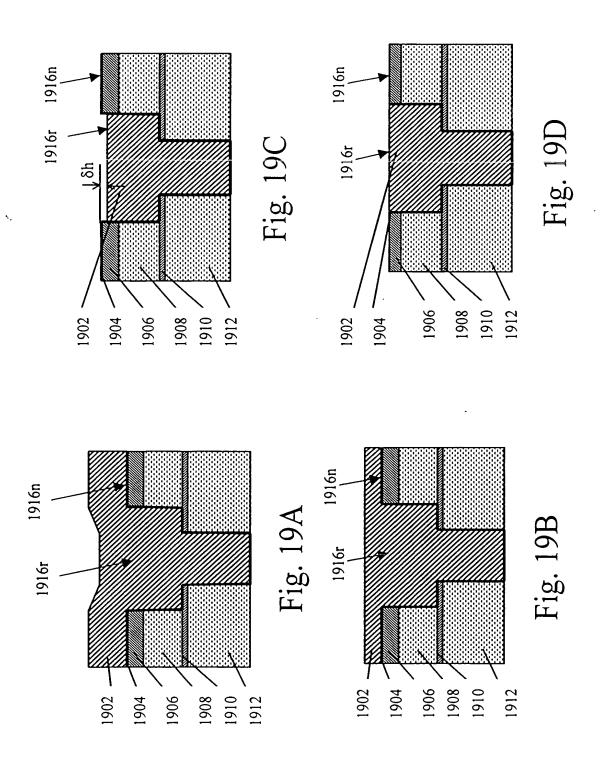


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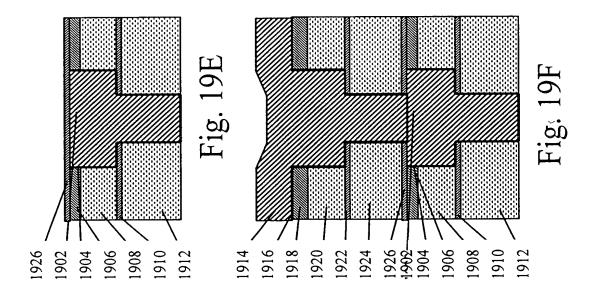
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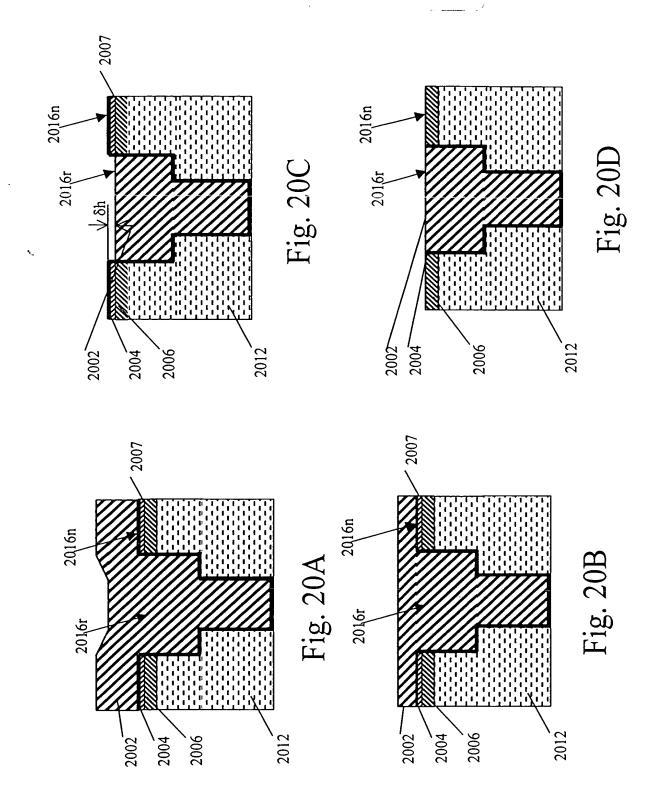
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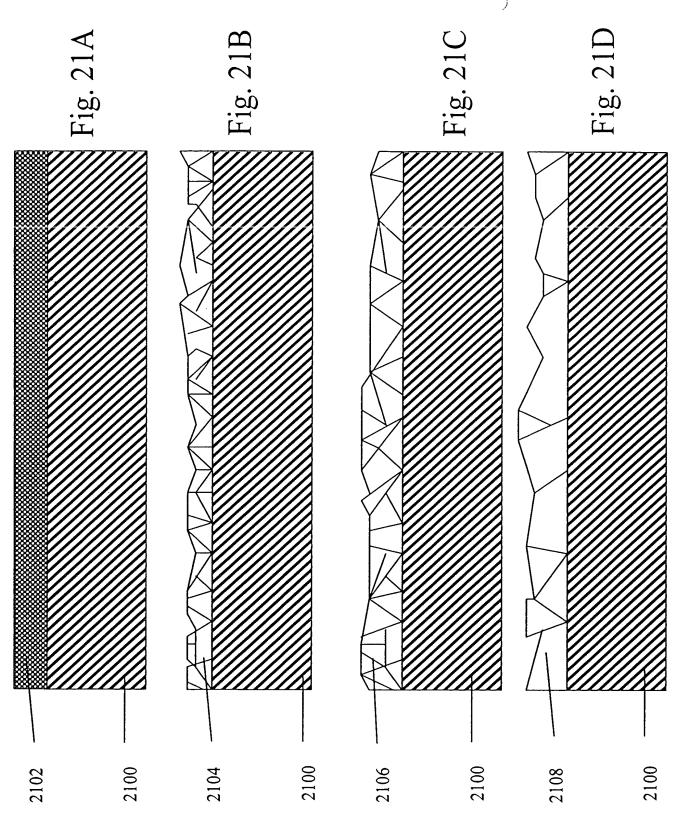


Fig. 22B

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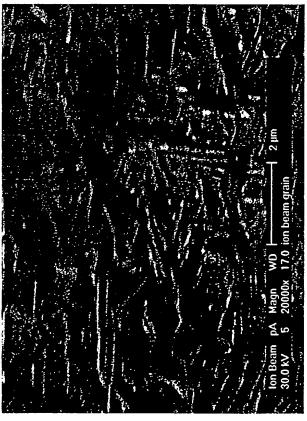
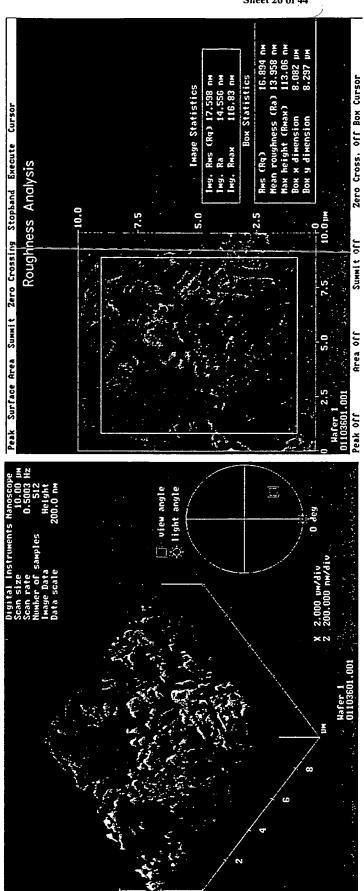
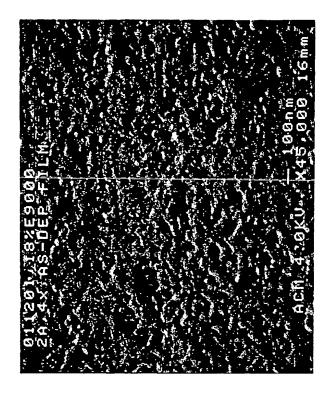


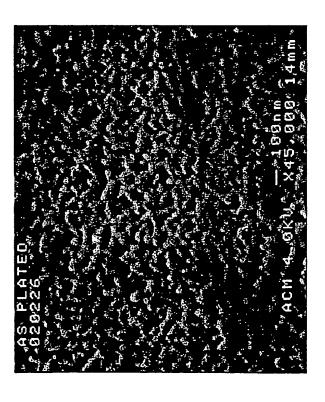
Fig. 22A



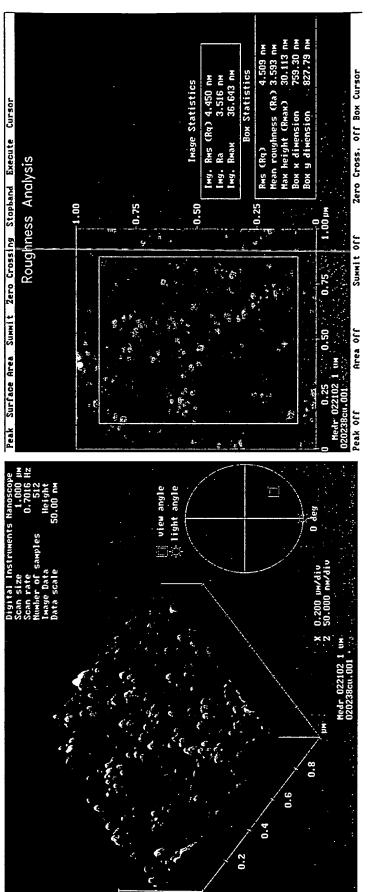


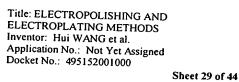
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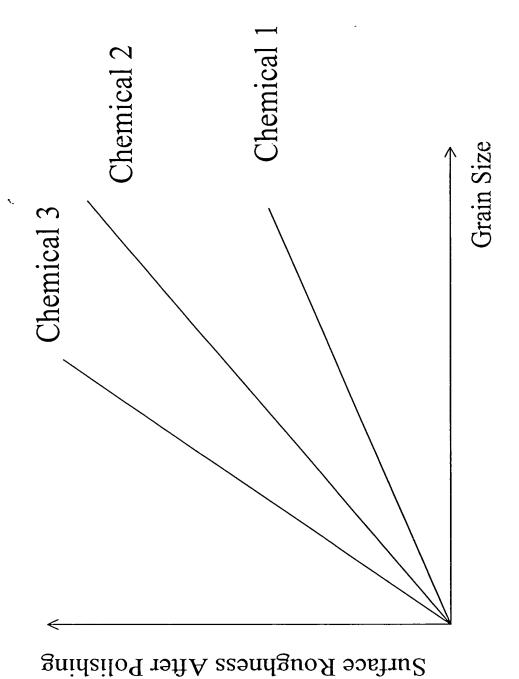
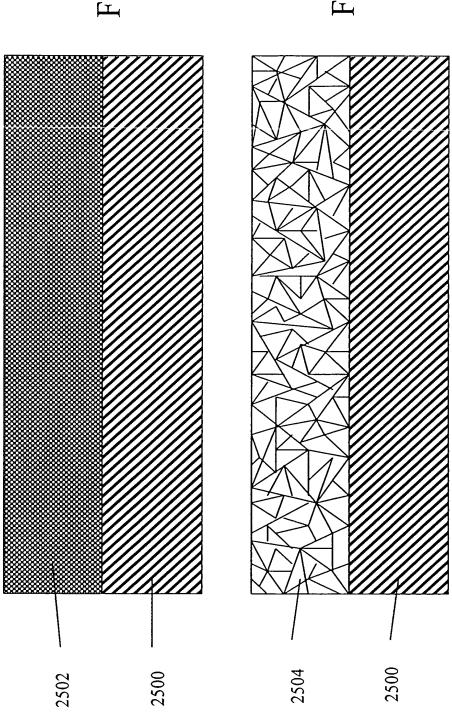
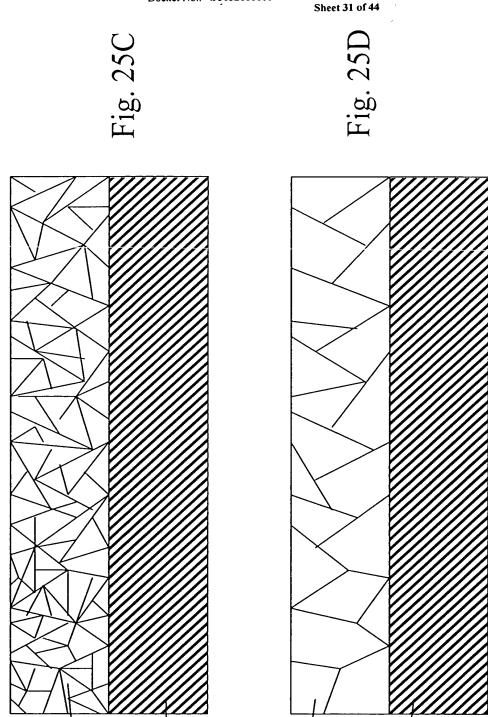
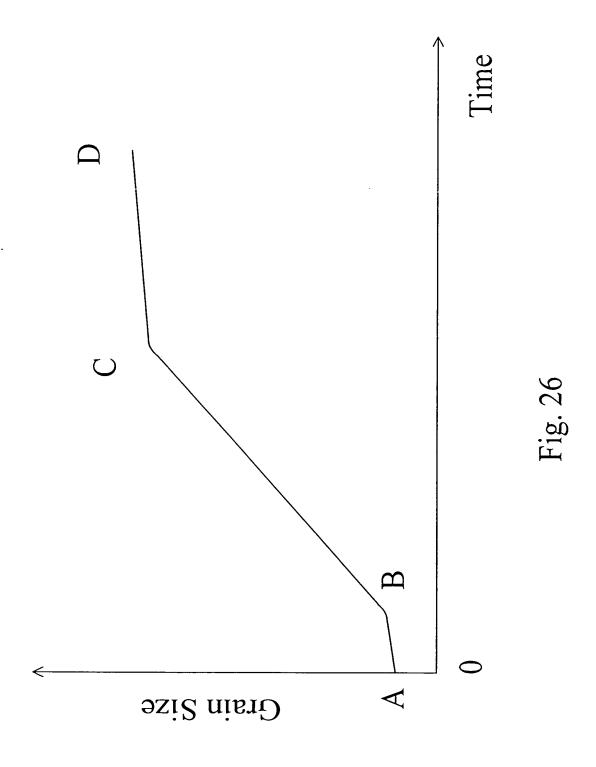


Fig. 25A 19. 25A 19. 25B

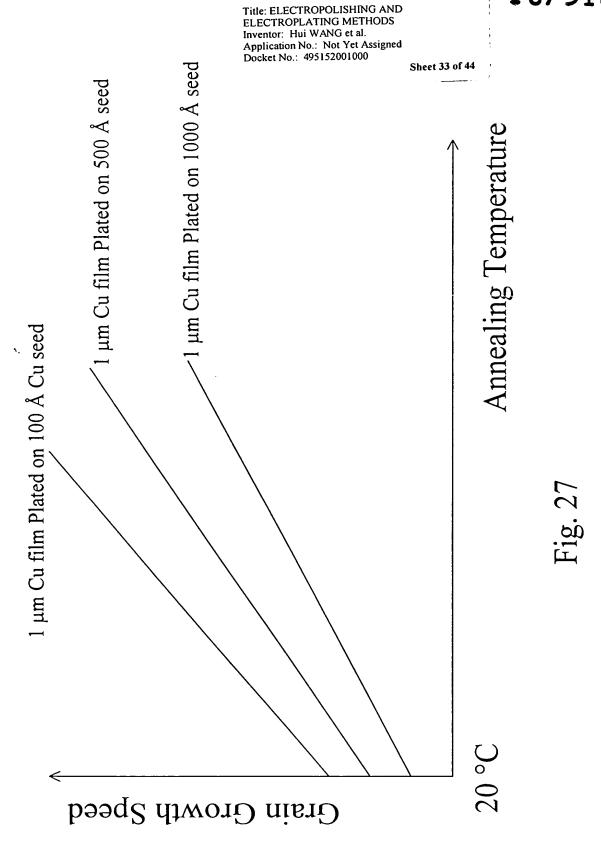




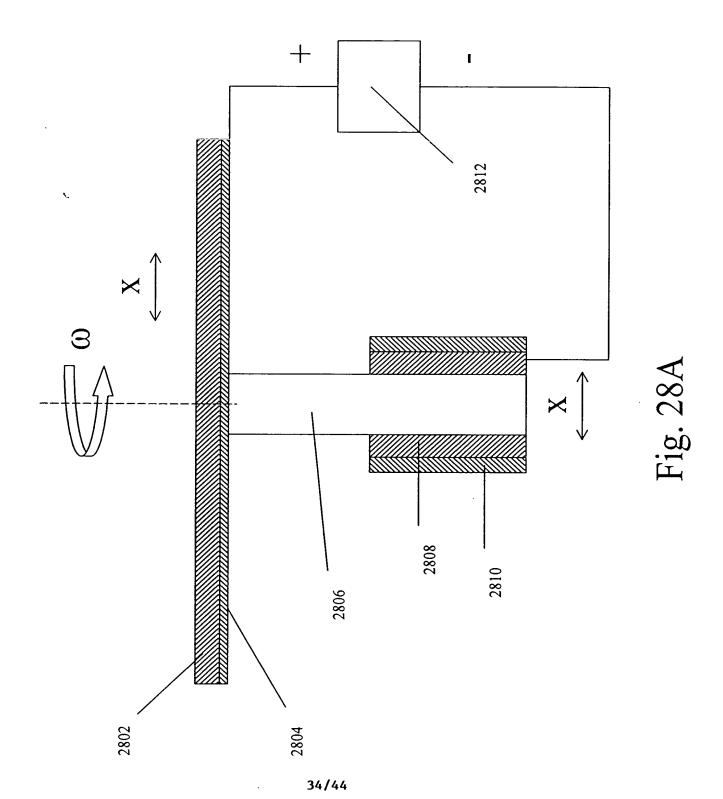
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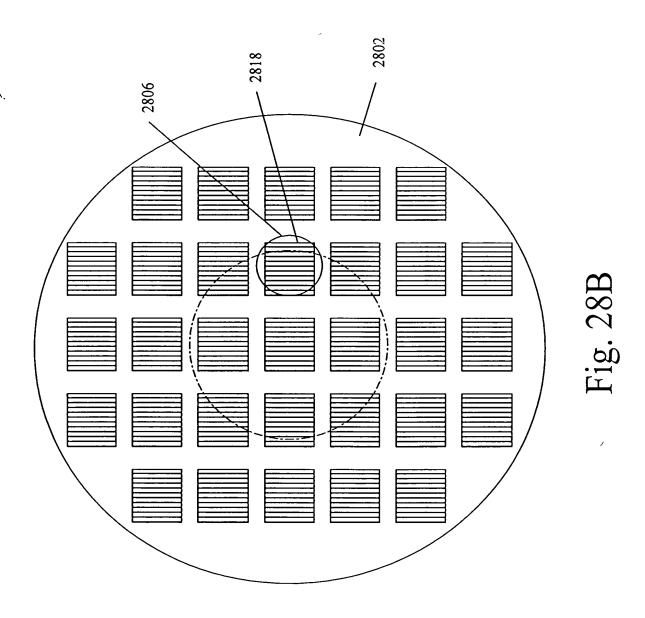
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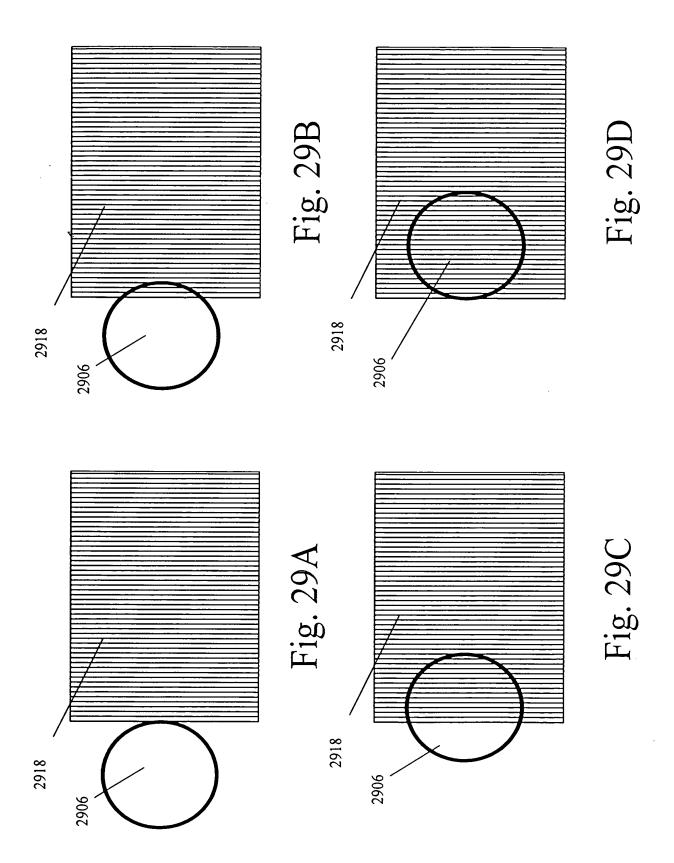
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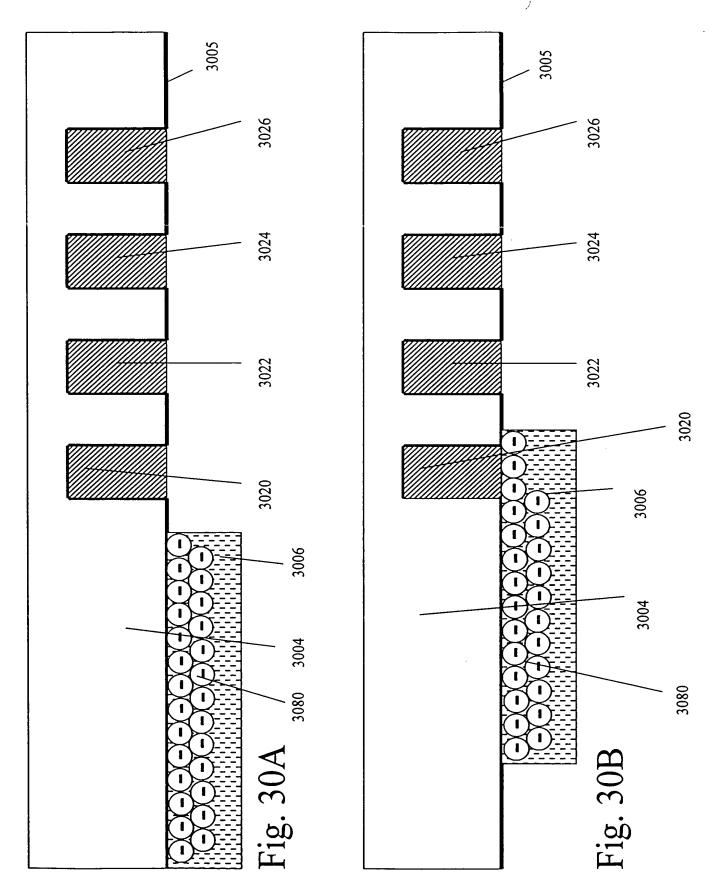
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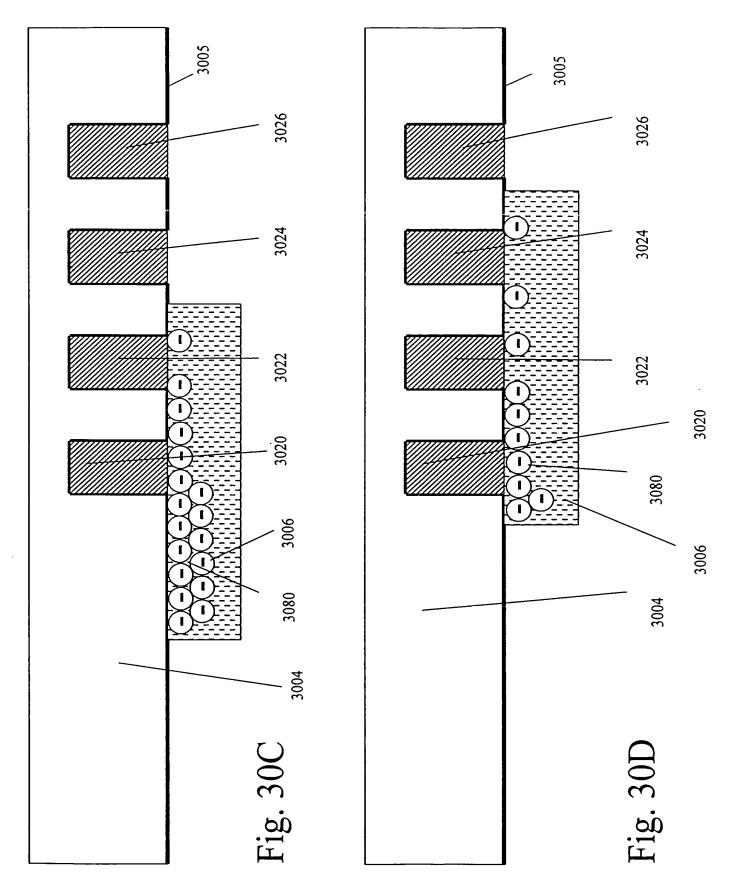
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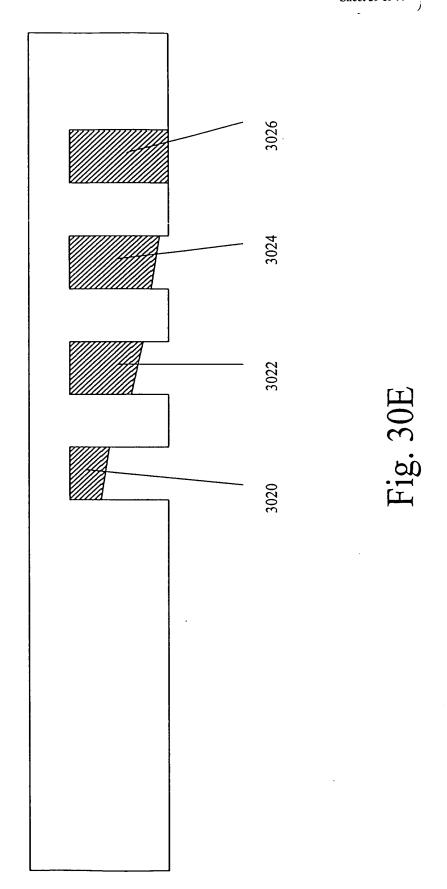
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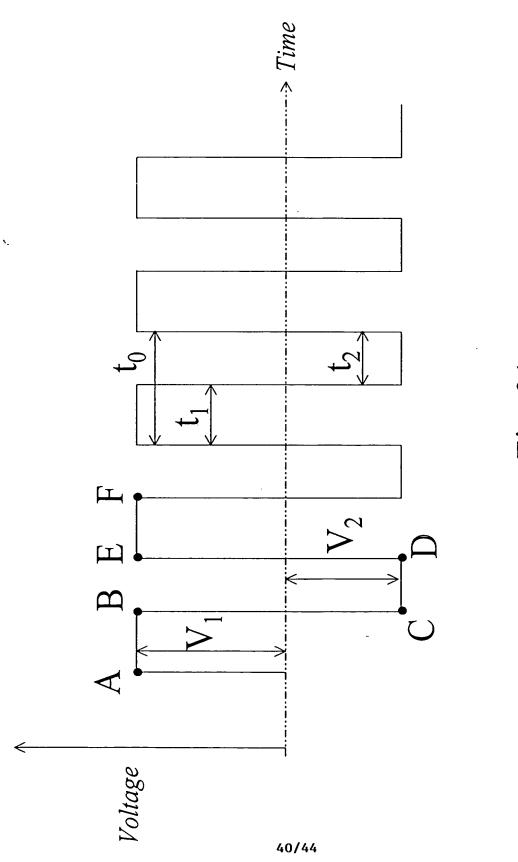
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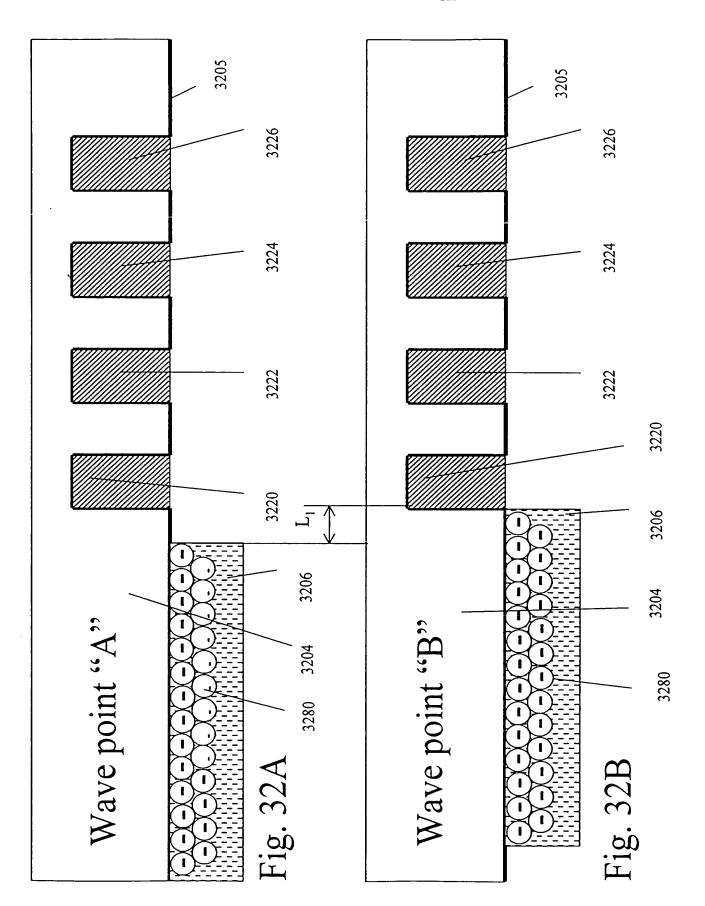
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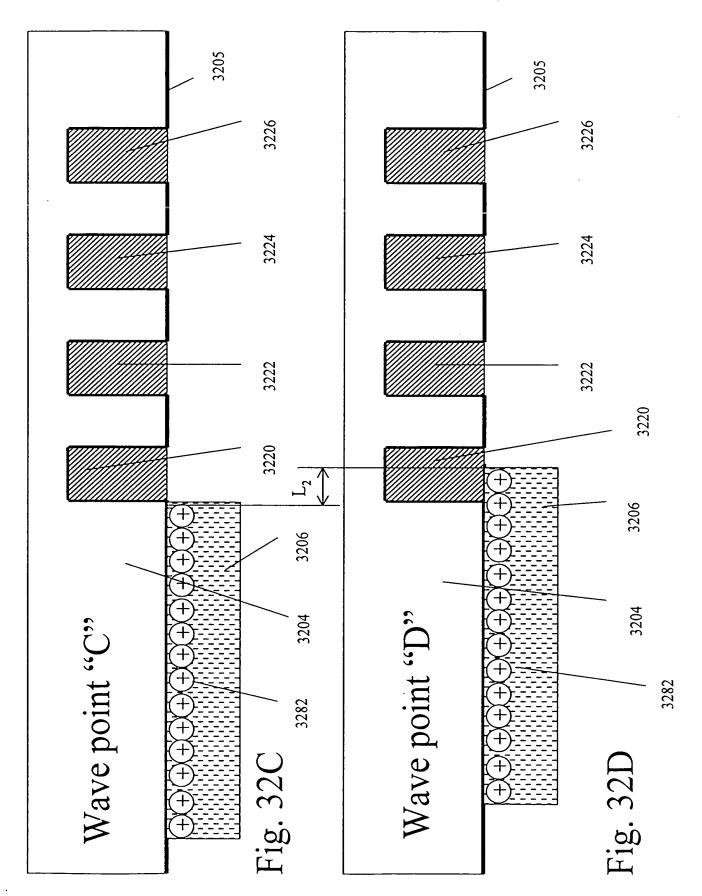
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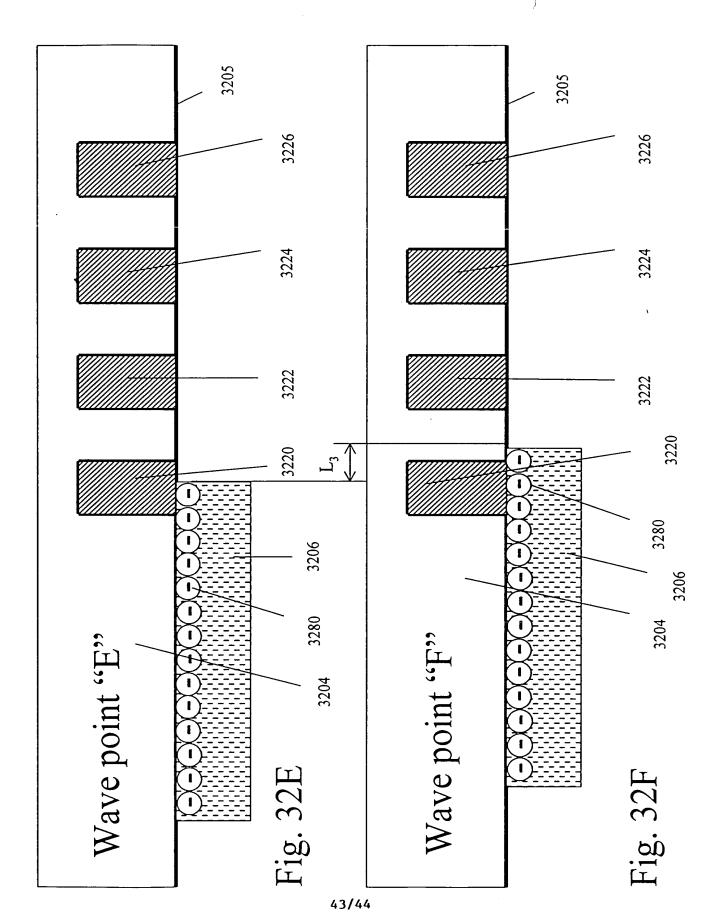
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